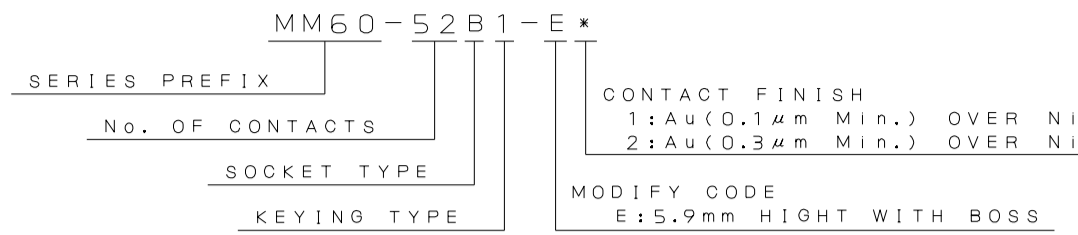


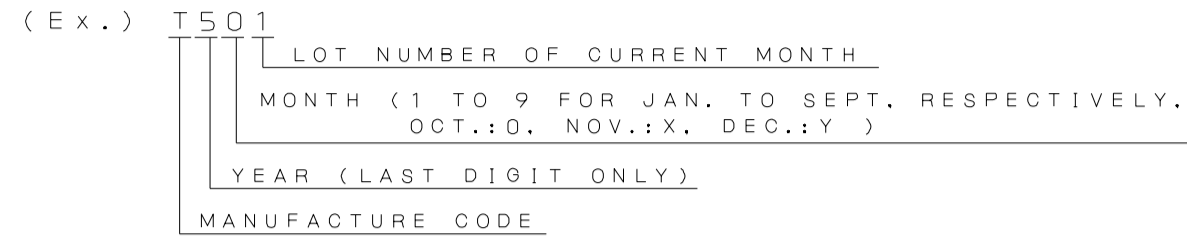
612501rs  
( 'ON ONIMVHD ) 台 架 圖

DESIGNATION



版 数 REV.	年 月 日 DATE	DCN NO.	变 更 内 容 DESCRIPTION	製 図 DR.	担 当 CHK.	查 閱 APPD.	承 認 APPD.
2	23.Jan.2006	059045	CHANGED BOSS LENGTH		Y.YAHIRO		K.HISATOMI
3	30.Mar.2015	012843	CORRECT AN ERROR		S.YAMAGUCHI	M.SASAKI	T.SHINDOU

NOTE 1. PRODUCTION LOT No. AS INDICATED.



NOTE 2. CARD THICKNESS APPLIES ACROSS TABS AND INCLUDES PLATING AND/OR METALIZATION.

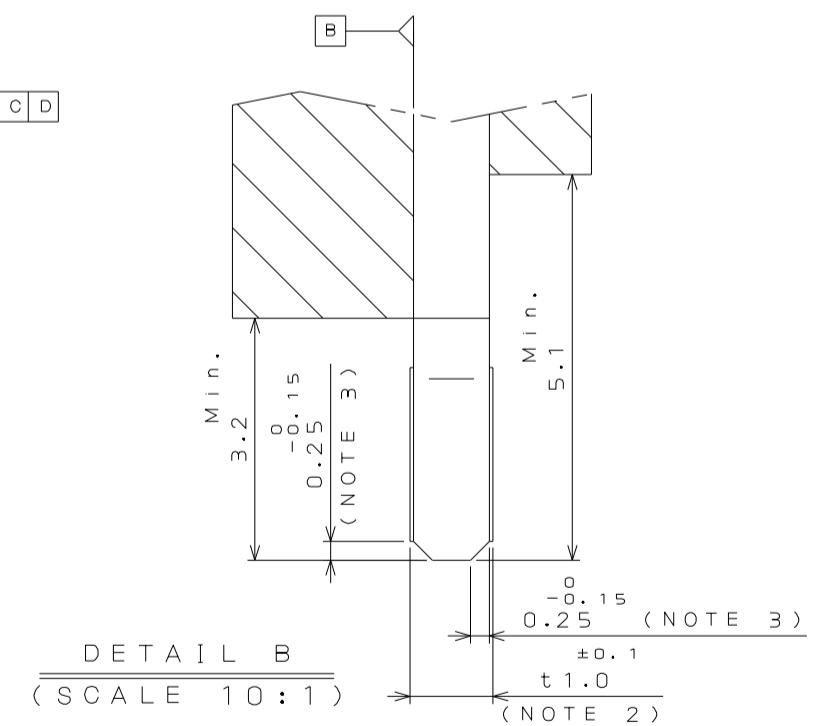
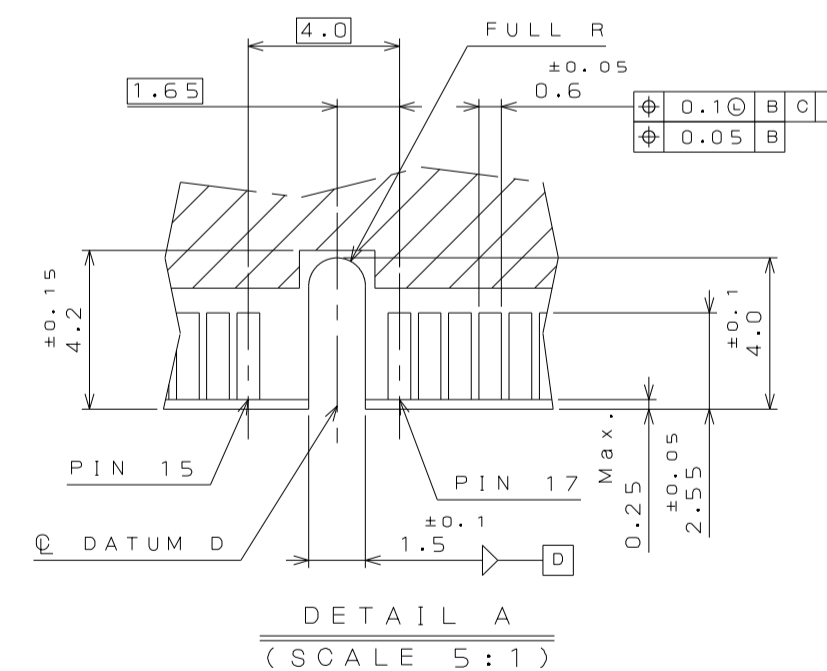
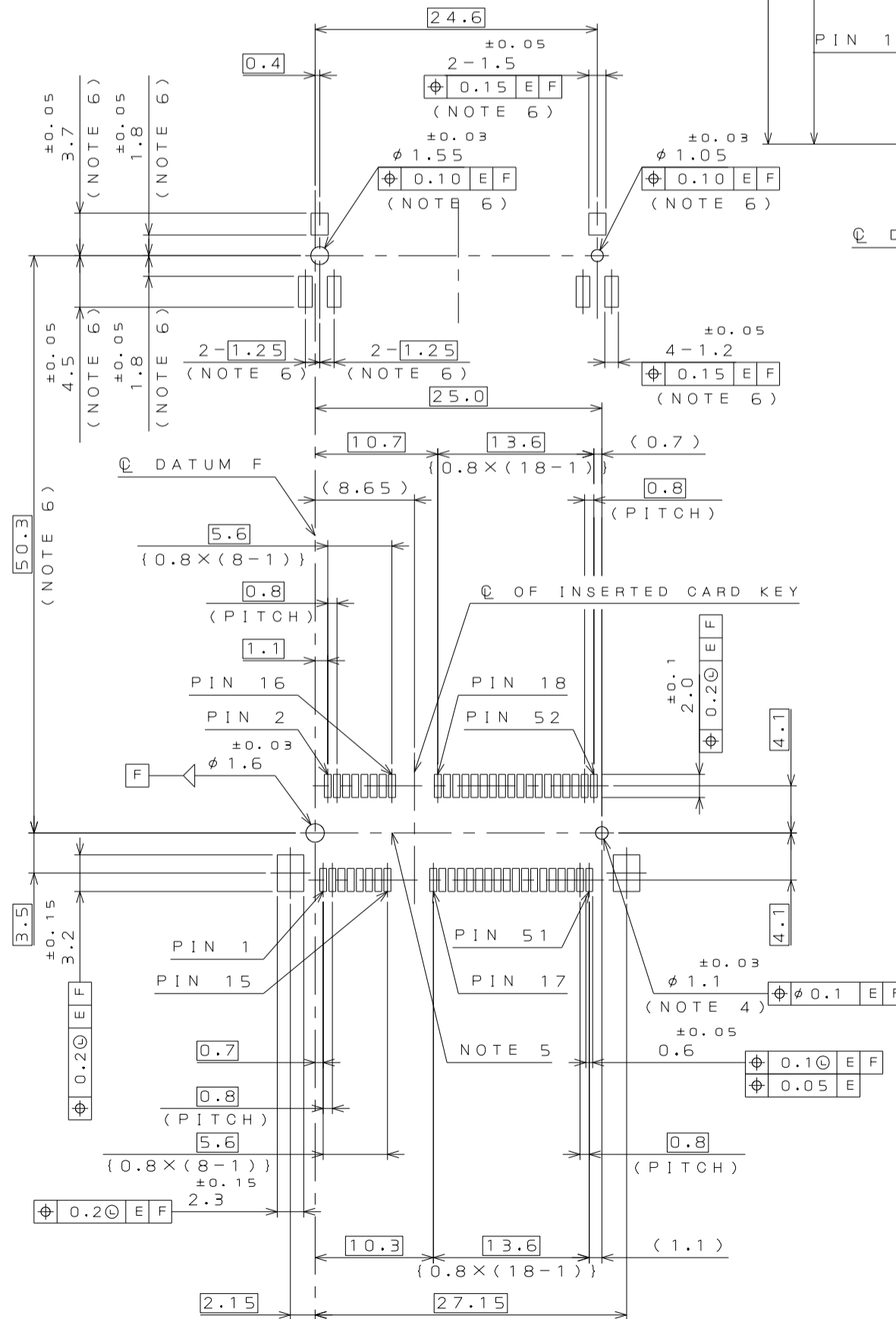
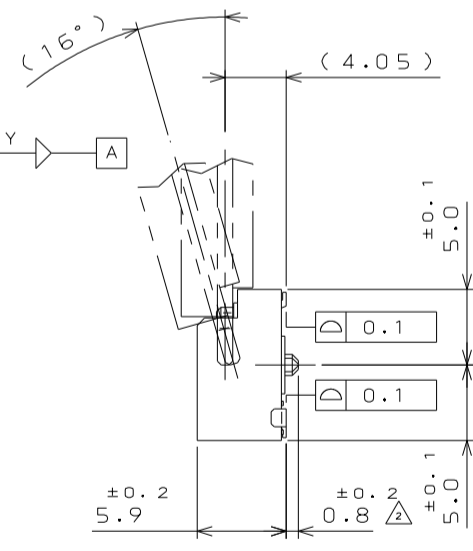
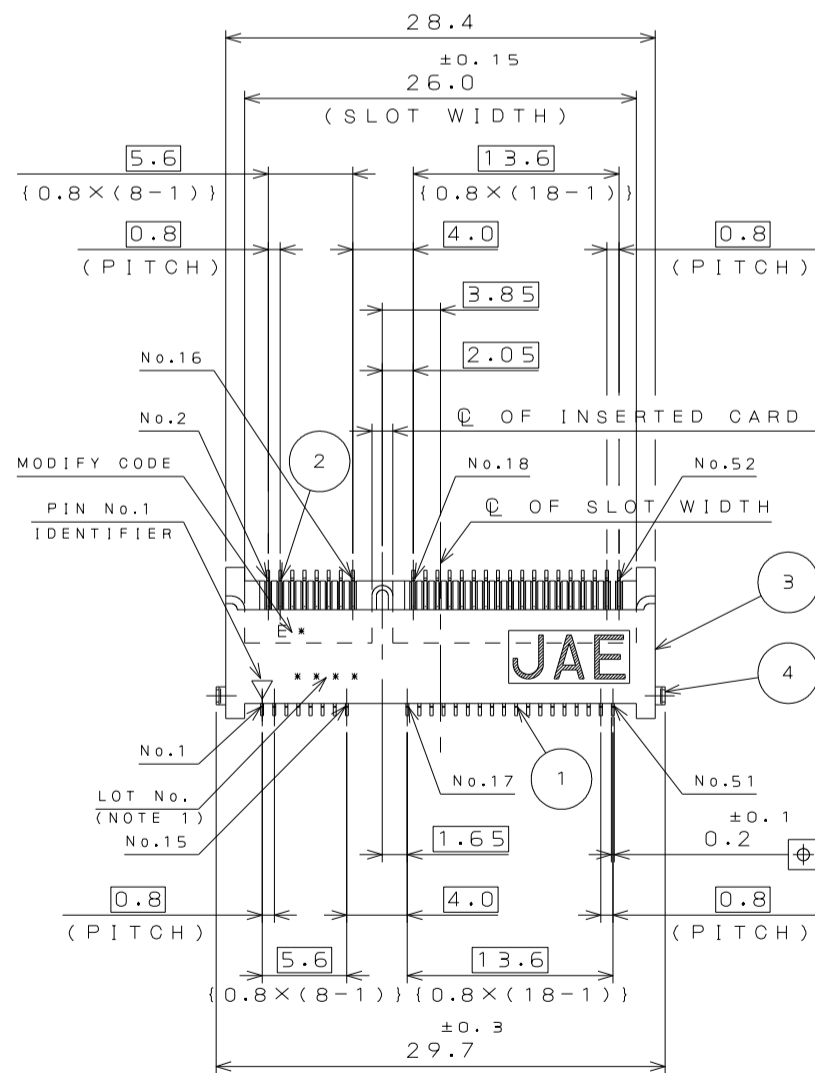
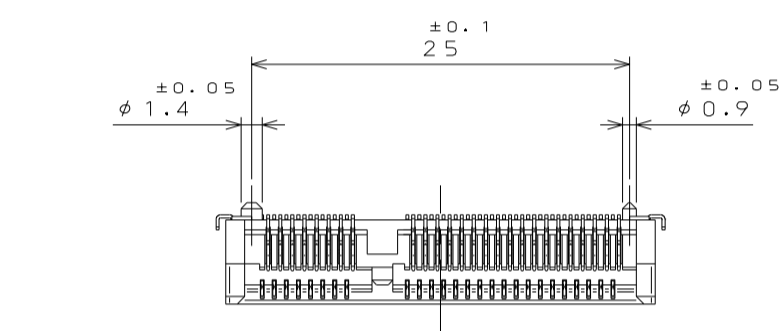
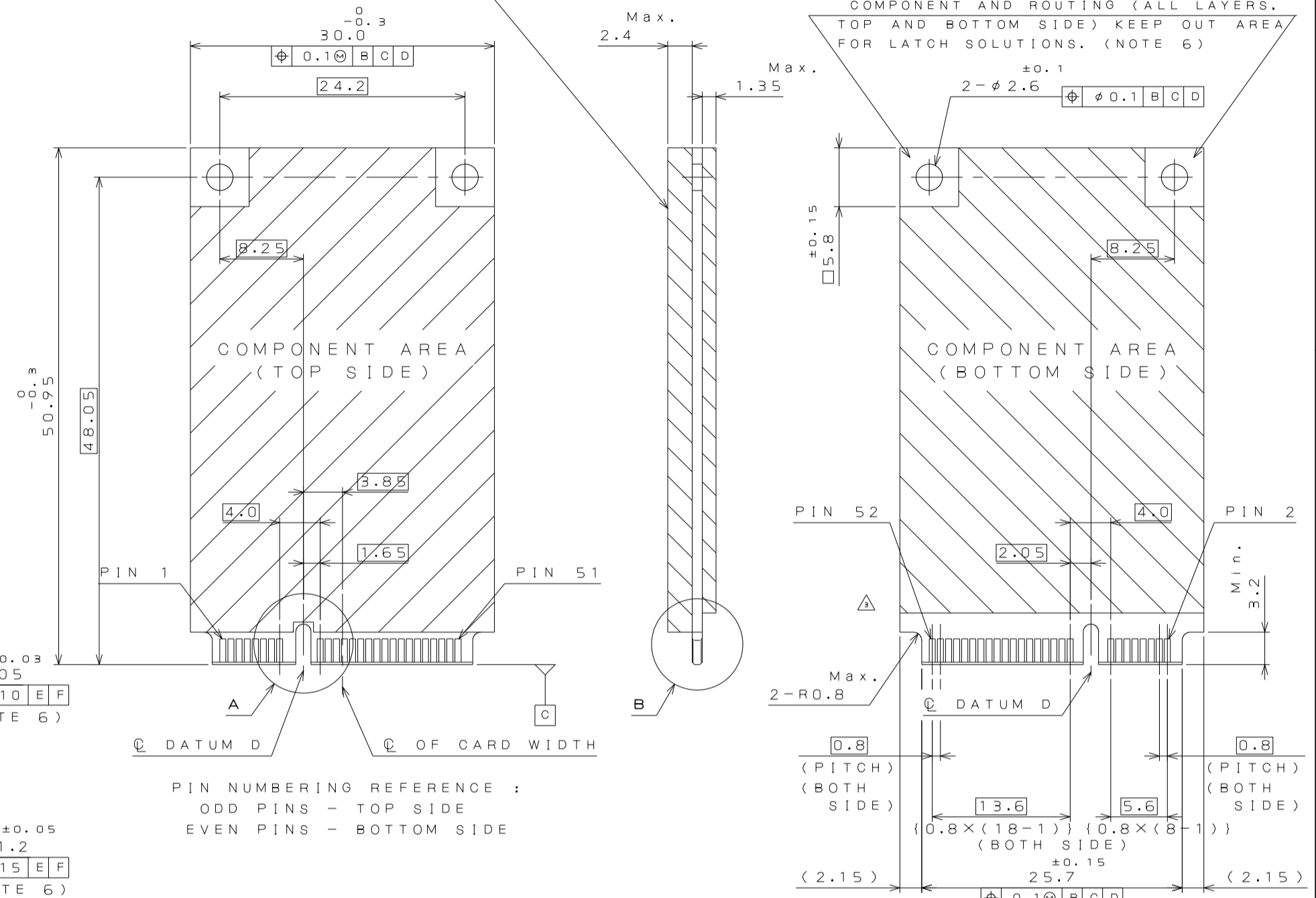
NOTE 3. BEVEL MUST BE FREE OF CUTTING BURRS.

NOTE 4. THE HORIZONTAL AXIS FOR THE PATTERN IS ESTABLISHED BY A LINE THROUGH THE CENTER OF THE  $\phi 1.6$  AND  $\phi 1.1$  HOLES. THE VERTICAL AXIS IS 90° TO THE HORIZONTAL AXIS, THROUGH THE CENTER OF DATUM F.

NOTE 5. LOCATION OF INSERTED CARD EDGE IS ALIGNED WITH  $\phi$  OF HOLES.

NOTE 6. ONLY WHEN THE LATCH SHOWN IN SJ105221(MM60-EZH059-B5) IS USED, THESE DIMENSIONS ARE APPLIED.

HATCHED AREAS ILLUSTRATE MAXIMUM AVAILABLE COMPONENT VOLUME. APPLICABLE DIMM(REF.)



DATUM E IS THE TOP OF SURFACE OF PCB.  
APPLICABLE P.C.B. DIMENSION(REF.)  
適合基板寸法(参考)

4	HOLD DOWN	2	COPPER ALLOY	TIN PLATING	
3	INSULATOR	1	THERMOPLASTIC		UL94 V-0
2	BOTTOM SIDE CONTACT	26	COPPER ALLOY	CONTACT AREA : Au OVER Ni SOLDERING AREA : GOLD FLASH OVER Ni	
1	TOP SIDE CONTACT	26	COPPER ALLOY	CONTACT AREA : Au OVER Ni SOLDERING AREA : GOLD FLASH OVER Ni	
符号 NO.	名 称 DESCRIPTION	個 数 QTY.	材 料 MATERIAL	仕 工 FINISH	備 考 REMARKS
	JACS-10313			5. Dec. 2005	日本航空電子工業株式会社
	公差( GENERAL TOLERANCE )				
	寸法( DIMENSION )				
	角度( ANGLES )				
	. ±0.8				
	.x ±0.4				
	.xx ±0.1				
	.xxx ±				
	製 図 DR.				名 称( TITLE )
	担 当 CHK.		Y.YAHIRO		JAPAN AVIATION ELECTRONICS INDUSTRY, LTD.
	查 閱 APPD.				MM60-52B*-E*
	承 認 APPD.		K.HISATOMI		図 面 番 号( DRAWING NO. )
					SJ105219
					版 数( REV. )
					3